

SPEC SHEET (FOR REFERENCE)	SHEET No.	Rev.	Page.
	G05091A	1	1 of 1

**TYPE:6PC2302P1A \* \***

CHIP SIZE	0.56 * 0.43mm
WAFER SIZE	6inch
POSSIBLE DIE PER WAFER	64,000pcs

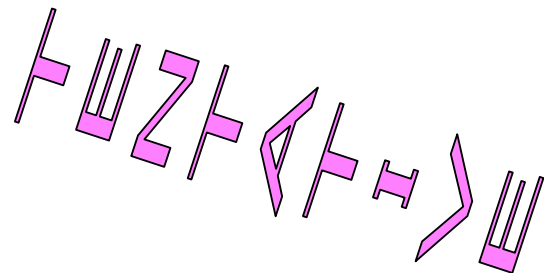
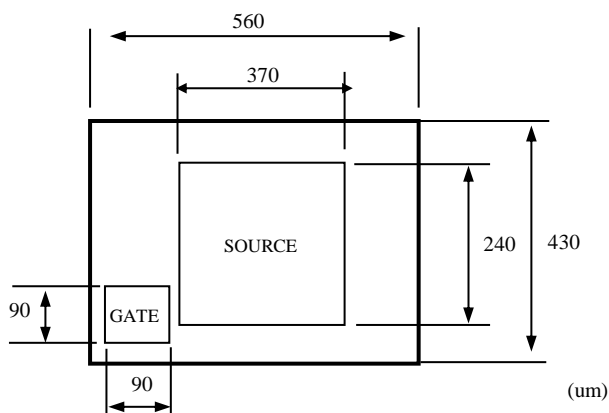
Maximum Ratings (Ta=25°C)

Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	-20	V
Gate-source voltage	VGSS	±8	V

WAFER PROBING SPEC (Ta=25°C)

TEST NO.	MODE	LIMIT				CONDITIONS
		MIN.	Typ	MAX.	UNIT	
1	IGSS1			±10	uA	VGS=±8V VDS=0V
2	IGSS2			±1	uA	VGS=±4.5V VDS=0V
3	IDSS			-500	nA	VDS=-20V VGS=0V
4	BVDSS	-23			V	ID=-250μA
5	VTH	-0.53		-1.2	V	ID=-250μA
6	RDS(on)1		0.25	0.36	ohm	VGS=-4.5V, ID=-350mA
7	RDS(on)2		0.37	0.55	ohm	VGS=-2.5V, ID=-300mA
8	RDS(on)3		0.55	1	ohm	VGS=-1.8V, ID=-150mA
9	VSD	-0.5		-1.1	V	I=-350mA VGS=0V
10	Yfs	200			mS	VDS=-10V Id=-200mA

※ Built-in ZD between Gate and Source



NOTE: